

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



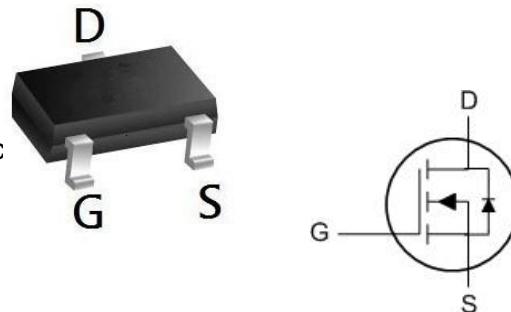
### Product Summary

BVDSS	RDS(ON)	ID
40V	19mΩ	7A

### Description

The XXW40N05L is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The XXW40N05L meet the RoHS and Green Prod



### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		40	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ\text{C}$	7.0	A
		$T_A = 100^\circ\text{C}$	4	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		32.8	A
EAS	Single Pulsed Avalanche Energy <sup>note2</sup>		13	mJ
$P_D$	Power Dissipation	$T_A = 25^\circ\text{C}$	2.0	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		73	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**N-Channel Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	40	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}$ , $V_{GS}=0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$ , $I_D=8\text{A}$	-	19	24	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=5\text{A}$	-	25	35	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=20\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	633	-	pF
$C_{oss}$	Output Capacitance		-	67	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	58	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=20\text{V}$ , $I_D=8\text{A}$ , $V_{GS}=10\text{V}$	-	12	-	nC
$Q_{gs}$	Gate-Source Charge		-	3.2	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	3.1	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}= 20\text{V}$ , $R_L = 2.5\Omega$ $V_{GS}=10\text{V}$ , $R_{REN} = 3\Omega$	-	4	-	ns
$t_r$	Turn-on Rise Time		-	3	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	15	-	ns
$t_f$	Turn-off Fall Time		-	2	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	7	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	32	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S= 8\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

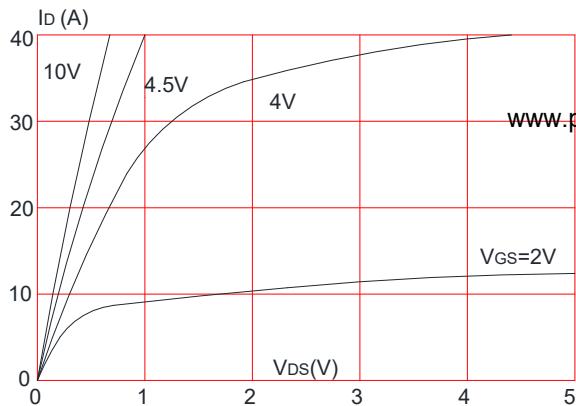
2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=20\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=7.2\text{A}$

$T_J=25^\circ\text{C}$ ,  $V_{DD}=-20\text{V}$ ,  $V_G= -10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=-8.4\text{A}$

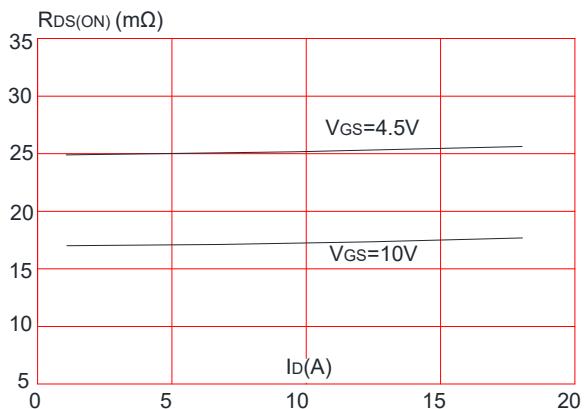
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$

## Typical Performance Characteristics-N

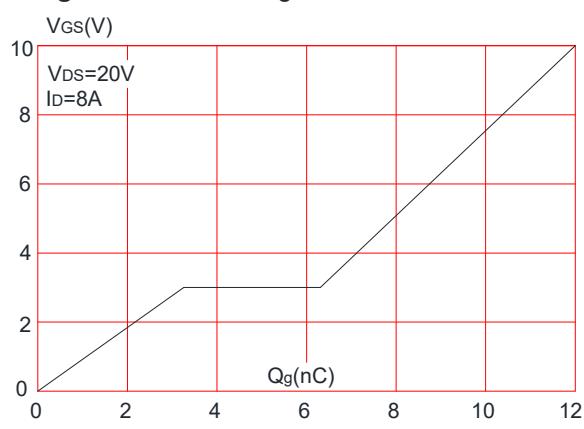
**Figure1:** Output Characteristics



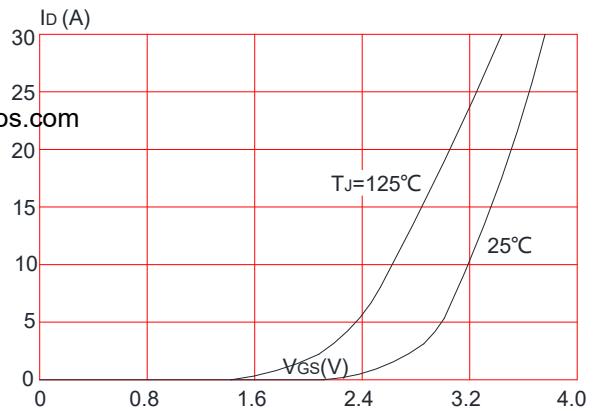
**Figure 3:** On-resistance vs. Drain Current



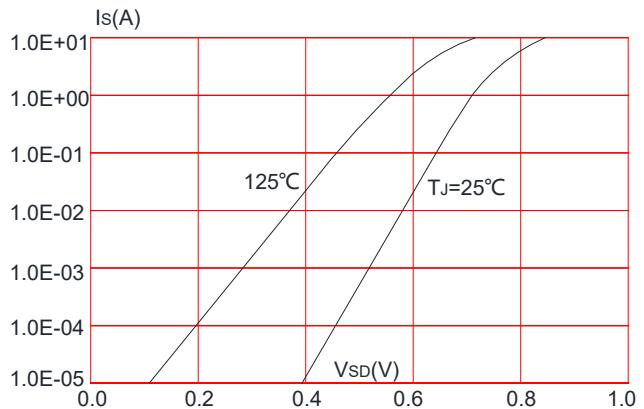
**Figure 5:** Gate Charge Characteristics



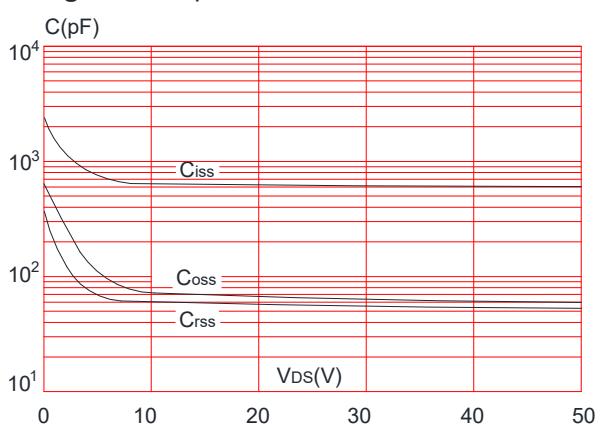
**Figure 2:** Typical Transfer Characteristics



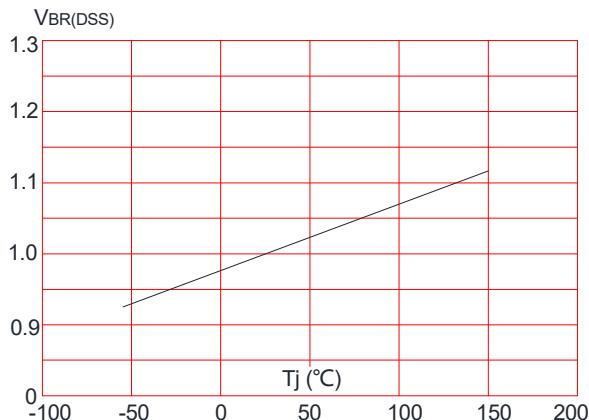
**Figure 4:** Body Diode Characteristics



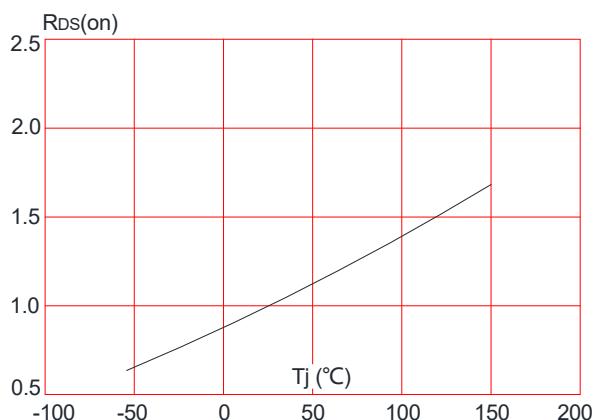
**Figure 6:** Capacitance Characteristics



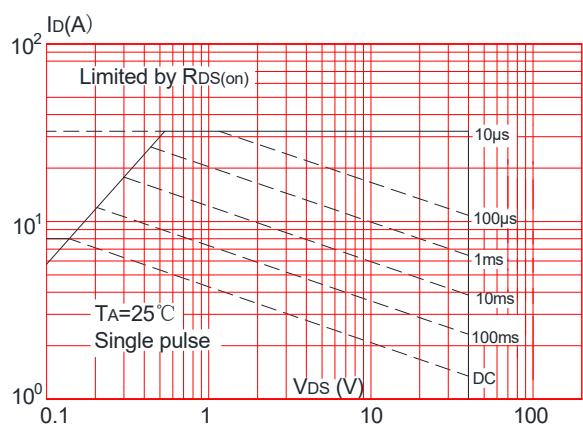
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



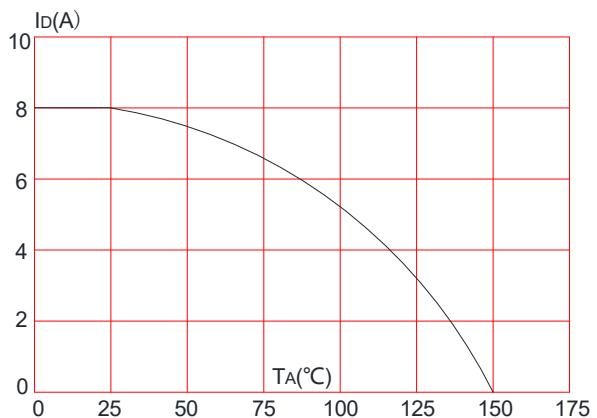
**Figure 8:** Normalized on Resistance vs. Junction Temperature



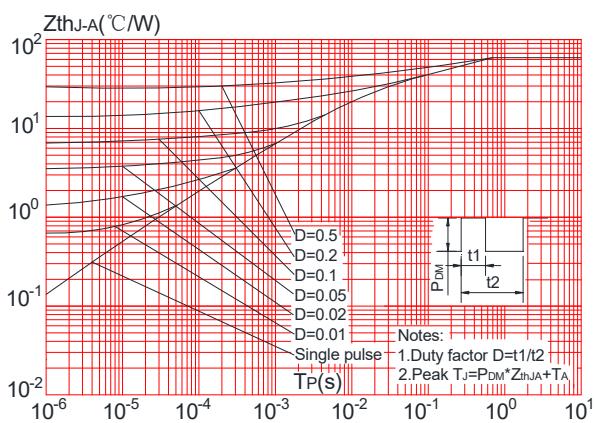
**Figure 9:** Maximum Safe Operating Area

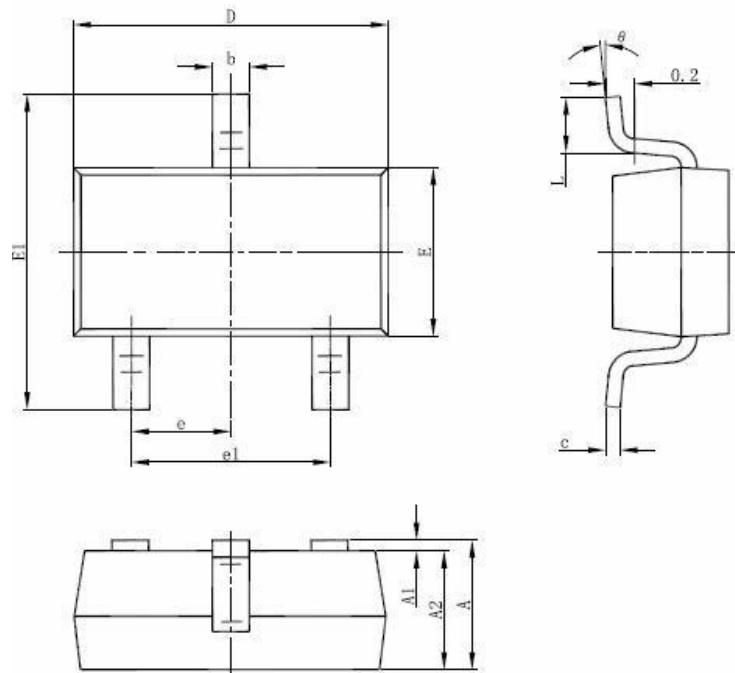


**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**N-Ch 40V Fast Switching MOSFETs**
**SOT-23-3L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°